

PRODUCTS DATA

FORMOSA No Clean Solder Paste

Model: SH-10882

Specification:

NO	Item	Specification	Standard
1	Appearance	Gray paste , No foreign , No Stiff	
2	Alloy	Sn10/Pb88/Ag2	JIS-Z-3282
3	Melting Point	268-290°C	DSC
4	Particle Size	(Type 3) +45µm 1% large , -20µm 10% less (Type 4) +38µm 1% large , -20µm 10% less	IPC-TM-650, 2.2.14
5	Powder Shape	Sphere	
6	Flux Content	9.5 ± 0.5wt%	JIS-Z-3197, 6.1
7	Halide Content	0.05 ± 0.02wt% (in flux)	JIS-Z-3197, 6.5
8	Viscosity	200 ± 30 Pa.s (25±1°C, 10rpm, Malcom)	JIS-Z-3284, Annex 6
9	Flux Type	ROL0	J-STD-004

Physical Properties & Reliability Data

No	Test Item	Test Result	Test Method
1	Copper Plate Corrosion Test	PASS	JIS-Z-3197, 6.6.1
2	Spread Test	90% up	JIS-Z-3197, 6.10
3	Silver Chromate Test	PASS	IPC-TM-650, 2.6.33
4	Copper Mirror Test	PASS	IPC-TM-650, 2.6.32
5	Fluorides By Spot Test	PASS	IPC-TM-650, 2.3.35.1
6	S.I.R Test ▲	1×10 ⁹ up	JIS-Z-3284, Annex 3
7	Electro Migration Test ◆	1×10 ¹² up Pass	JIS-Z-3284, Annex 14
8	Viscosity Test(25°C, 10rpm)	200 ± 30 Pa.s	JIS-Z-3284, Annex 6
9	Tack Test (KN/m ²)	128(8hr)	JIS-Z-3284, Annex 9
10	Slump Test	Less than 0.3 mm	JIS-Z-3284, Annex 8
11	Solder Ball Test	PASS	JIS-Z-3284, Annex 11

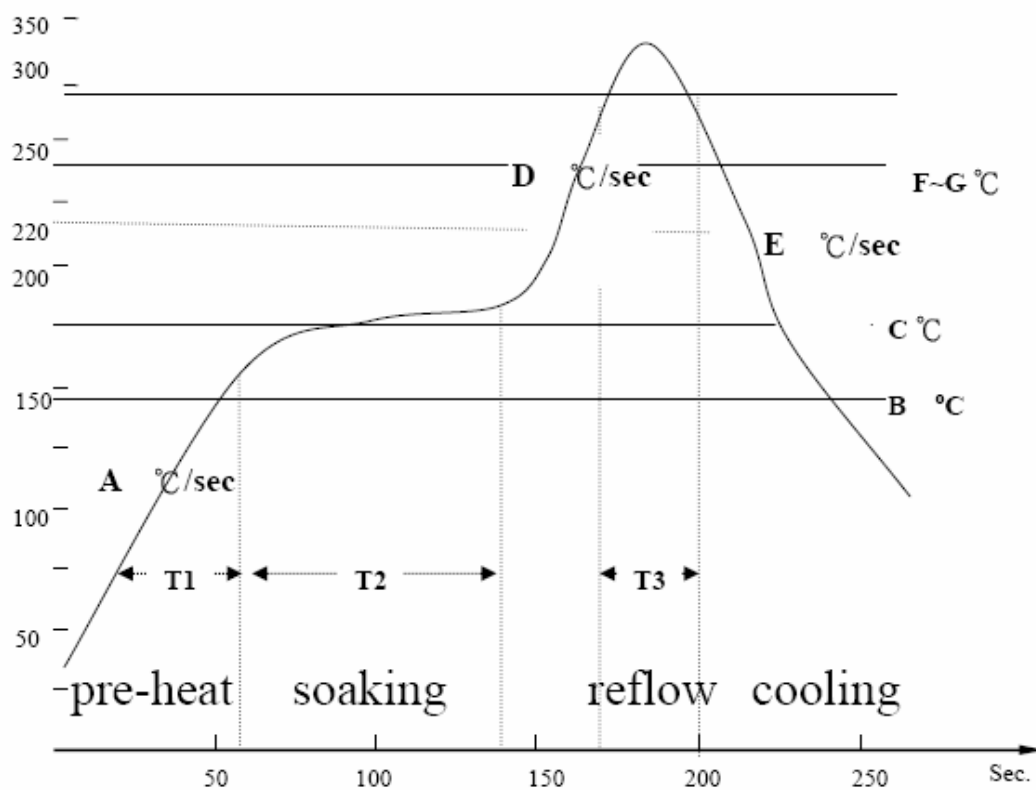
▲ Test Conditions : 85°C , 85% RH

◆ Test Conditions : 40°C , 95% RH

ALLOY COMPOSITION

(Sn)	(Ag)	(Pb)	(Cu)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)
10	2	REM.	0.05	0.002	0.002	0.05	0.02	0.03	0.1	0.002
±1	±0.05		MAX	MAX	MAX	MAX	MAX	MAX	MAX	MAX

Temperature Profile



- A: ramp up rate during preheat: 2.0~4.0 °C/sec
- B~ C : soaking temperature: 165~195 °C
- D: ramp up rate during reflow: 1.2~2.3 °C/sec
- E: ramp down rate during cooling: 1.7~2.2 °C/sec
- F-G : peak temperature: 320~340 °C
- T1: preheat time: 50~80 sec
- T2 : dwell time during soaking: 60~120 sec
- T3 : time above 290 oC : 40~80 sec



No-Clean
High Temperature
Solder Paste



Handling and Storage Instruction

1. Storage

- (1) Keep in 0~10°C temperature.
- (2) Expiration period: 6 months from production date (sealed condition).
- (3) Keep out of direct sunlight.

2. Operation Manual (Sealed)

- (1) Keep solder paste in room temperature ($25 \pm 2^\circ\text{C}$) for 3~4 hours. Do not use any heater to raise temperature.
- (2) Kindly mixed averagely for 1~3 minutes according to necessity.

3. Operation Manual (Opened)

- (1) At first, add 2/3 can of solder paste onto the stencil, do not add more than 1 can of which.
- (2) Add solder paste a little at a time according to production procedure.
- (3) To maintain the solder paste quality, please make sure not to storage the opened can with sealed can.
- (4) Use new opened solder paste at the beginning of the next day. Mix opened solder paste with sealed one at ratio 1:2, add a little at a time during printing.
- (5) Soon after printing, please make sure all components to be mount on printed circuit board between 4~6 hours.
- (6) Please withdraw solder paste from stencil and seal kindly if printing progress would pause for more than 1 hour.
- (7) After continuously printing for 24 hours, kindly withdraw printed solder paste and follow step (4).
- (8) It is recommended to clean both side of stencil every 4 hours manually to ensure printing quality.
- (9) Kindly keep room temperature between 22~28°C, room humidity RH 30~60% is recommended.
- (10) To clean up the defect printed board, kindly use isoprophyl alcohol or IPA.

Contact Information



Tel/Fax: (+98) 711 227 2688

<http://www.pishrokhotoo.s5.com>

**No.12-Bagh Safa building-Bagh
Safa Lane-Azadi Blvd-Shiraz-Iran**